

The Benefits of Multi-Lingual Extensions to IBIS

Stéphane Rousseau

PCB European Product Specialist

**Mentor
Graphics®**

Agenda

- **Simulation Limitations**
- **Advanced Modeling Capabilities**
- **Modeling Alternatives:**
 - **Altera Stratix GX High-Speed Serial Interface (HSSI)**
- **Conclusions**

Simulation Limitations

- **Model availability remains an issue**
 - Proprietary models and languages limit industry mass adoption
- **IBIS has major limitations; customers can't use it exclusively**
 - Non-extensible syntax
 - Unable to model today's buffer technology
 - Adaptive drivers and receivers
 - Limitations in modeling power supply dynamics
- **SPICE has issues as well**
 - Too slow for analyzing entire design!!
 - Models often encrypted to proprietary formats
 - Vendors reluctant to provide the IP often found in SPICE models
- **Additional engine limitations exist**

Advanced Modeling Capability

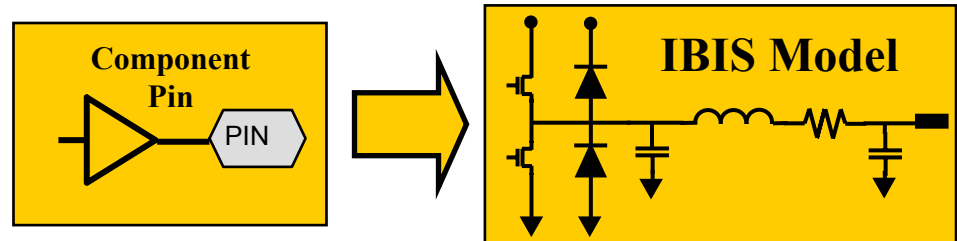
- **Allow customers to use models in any possible industry standard format**
 - **There are different model formats and languages in use today for high-speed design**
 - **IBIS**
 - **SPICE**
 - **HSPICE, Eldo, PSpice, ...**
 - **VHDL-AMS (IC level)**
- **By providing support for more than one, improve probability of finding a model**
- **Use the right model for the job at hand**

Extensions to IBIS

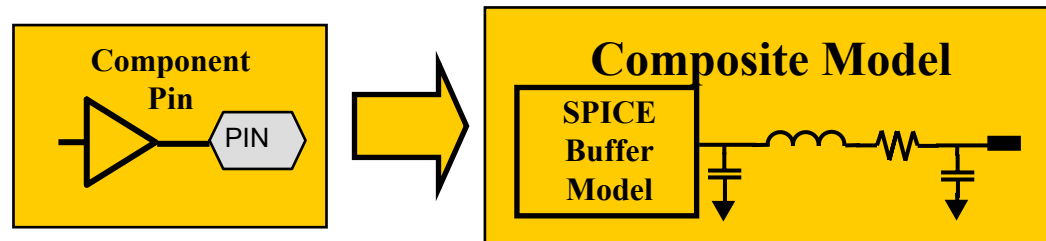
- **Allow IBIS models to reference external models through keywords**
 - **Standard language extensions**
 - **SPICE**
 - **VHDL-AMS**
 - **IBIS extensions**
 - **[External Model]**
 - **[External Circuit]**
 - **[Circuit Call]**
 - **[Node Declaration]**

I/O Buffer Examples

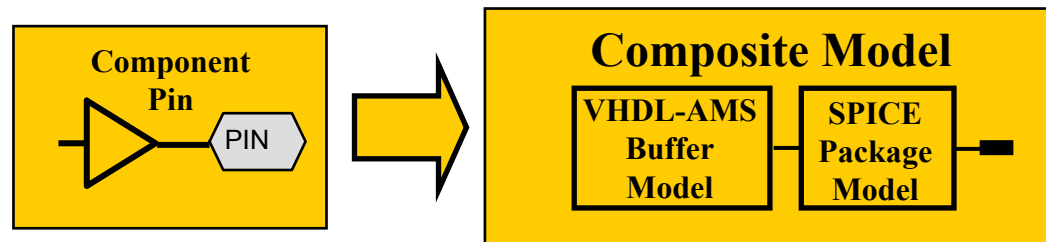
- IBIS only



- IBIS Parasitics with SPICE Buffer



- SPICE Parasitics with VHDL-AMS buffer



Multi-Lingual Simulation

- Mix and match driver model formats on a single net

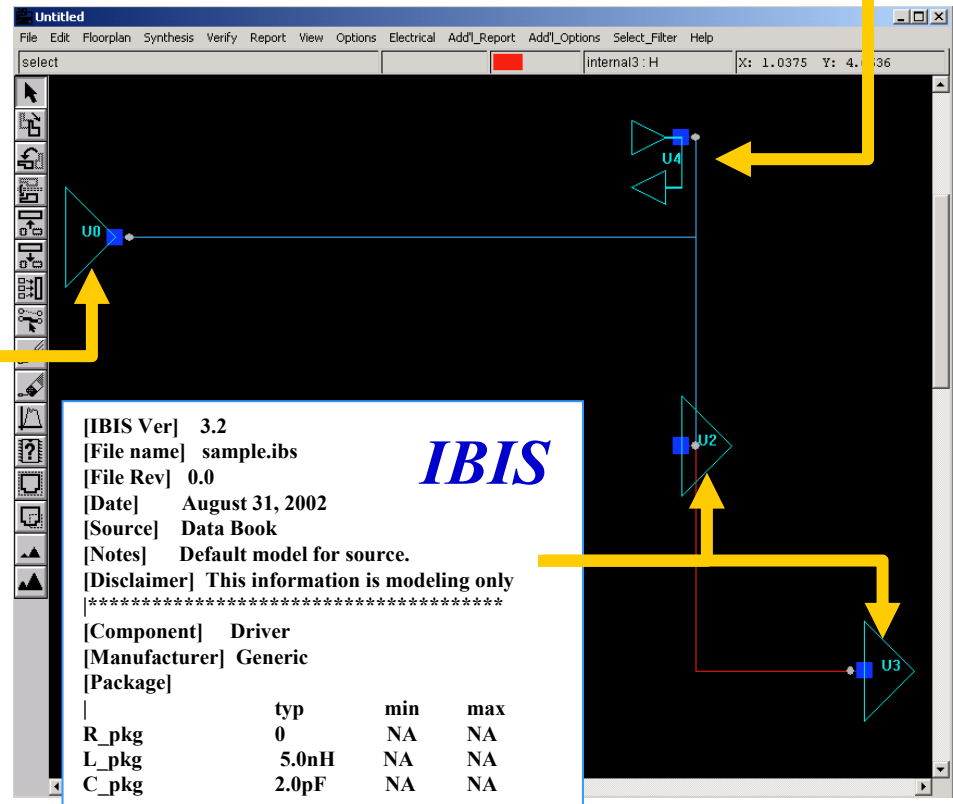
SPICE
 R_IS277 VCC out1 1.55K
 C_IS272 ibias N\$238 28.3P
 M_IS46 N\$240 ibias 0 0 NFET L=1.52U W=7.85U M=40
 M_IS283 out2 out2b VCC VCC PFET L=0.5U W=4U M=1
 .MODEL NFET NMOS (RSH=17 KP=1.34M
 + GAMMA=0.919 PHI=0.707 LAMBDA=0.1M RD=52.88
 + RS=52.55 CBD=4.79P CBS=5.73P PB=1
 + CGSO=3.17P CGDO=2.04P CGBO=4.01P MJ=0.189)
 ...

VHDL-AMS

```

entity ibis_tx_cmos is
generic (
  c_comp:real:=7.0e-12;
  vpudata:real_vector:=(-5.250000e+00, ... ,7.500000e+00);
  ipudata:real_vector:=( 3.555770e-01, ... ,-1.356870e-01);
  ... same for vpd, ipd, vpc,ipc, vgc, igc

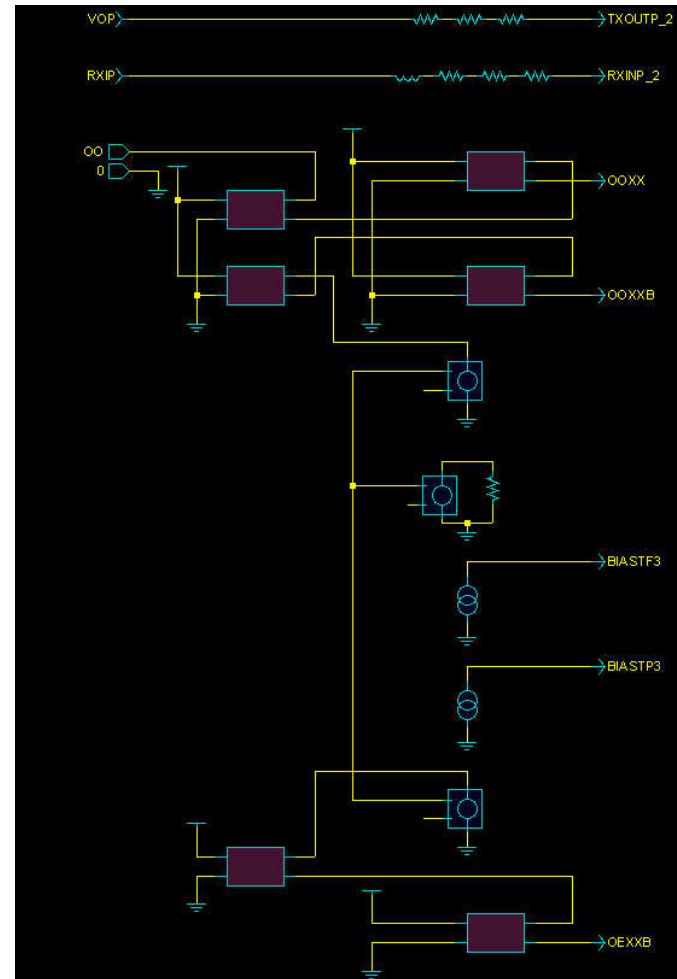
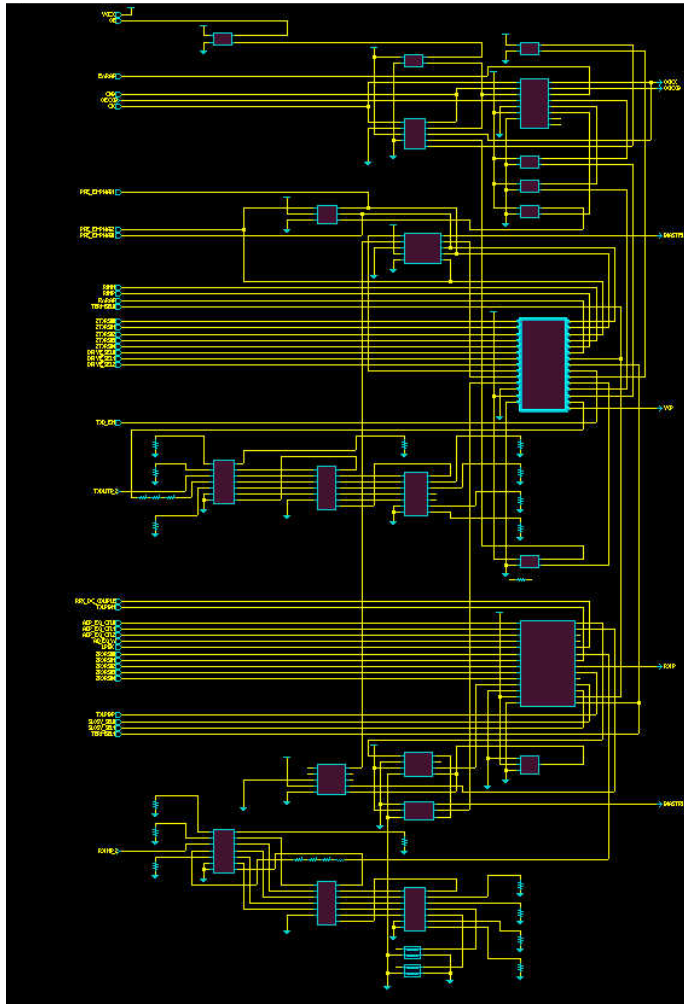
```



Modeling Alternatives: Starting Point

- **Altera Stratix GX High-Speed Serial Interface (HSSI)**
 - **SPICE transistor level model**
 - **Single circuit for transceiver**
 - **Selectable parameters for Driver pre-emphasis levels, Driver output voltage amplitude, Driver impedance, Receiver equalization level, Receiver impedance, Trace length and loss**
- **3” lossy differential pair trace model from driver pins to receiver pins**
- **Circuit as delivered took 21 minutes (real time) to simulate in Eldo (SPICE)**

Original Transceiver Model



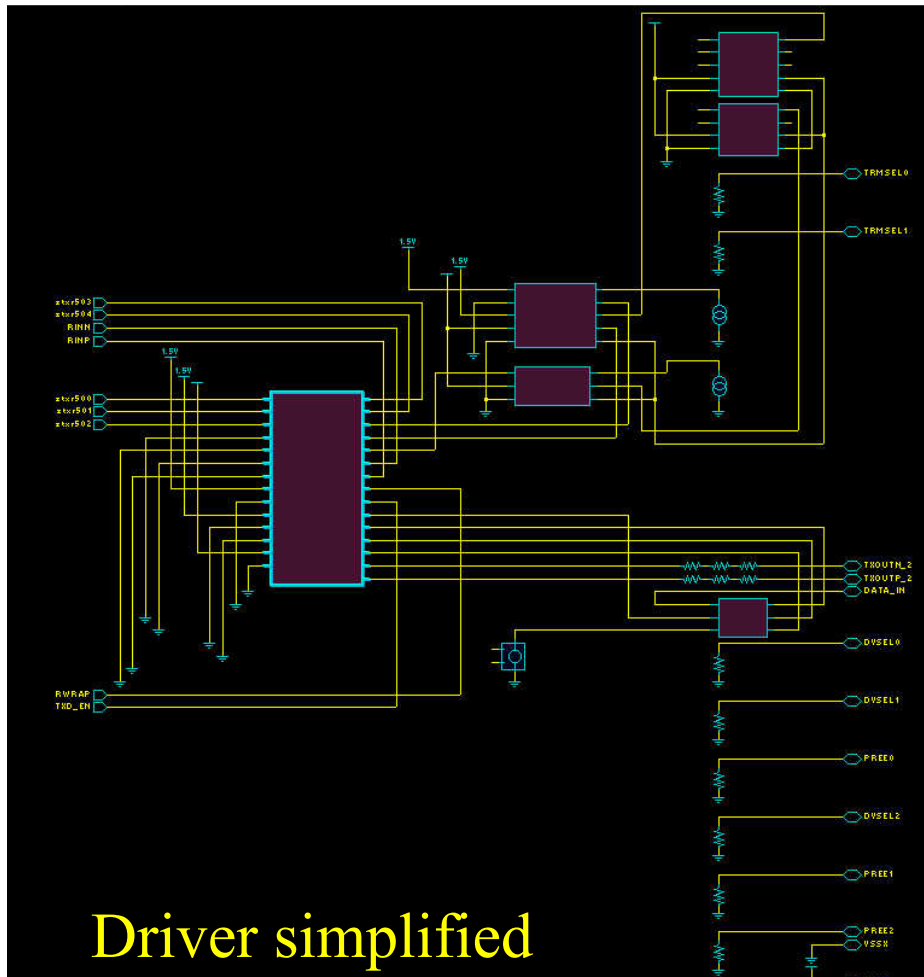
Multi-page schematic created with SpiceVision PRO from Concept Engineering

Issues with SPICE Models

- **Can't simulate Driver separate from receiver**
 - Probably simulating extra nodes that are irrelevant
- **Subcircuits encrypted (Eldo)**
- **Global nodes (.global in SPICE)**
 - Possible conflict with models from another source
- **Scale option = 1u**
 - Another possible conflict with other models

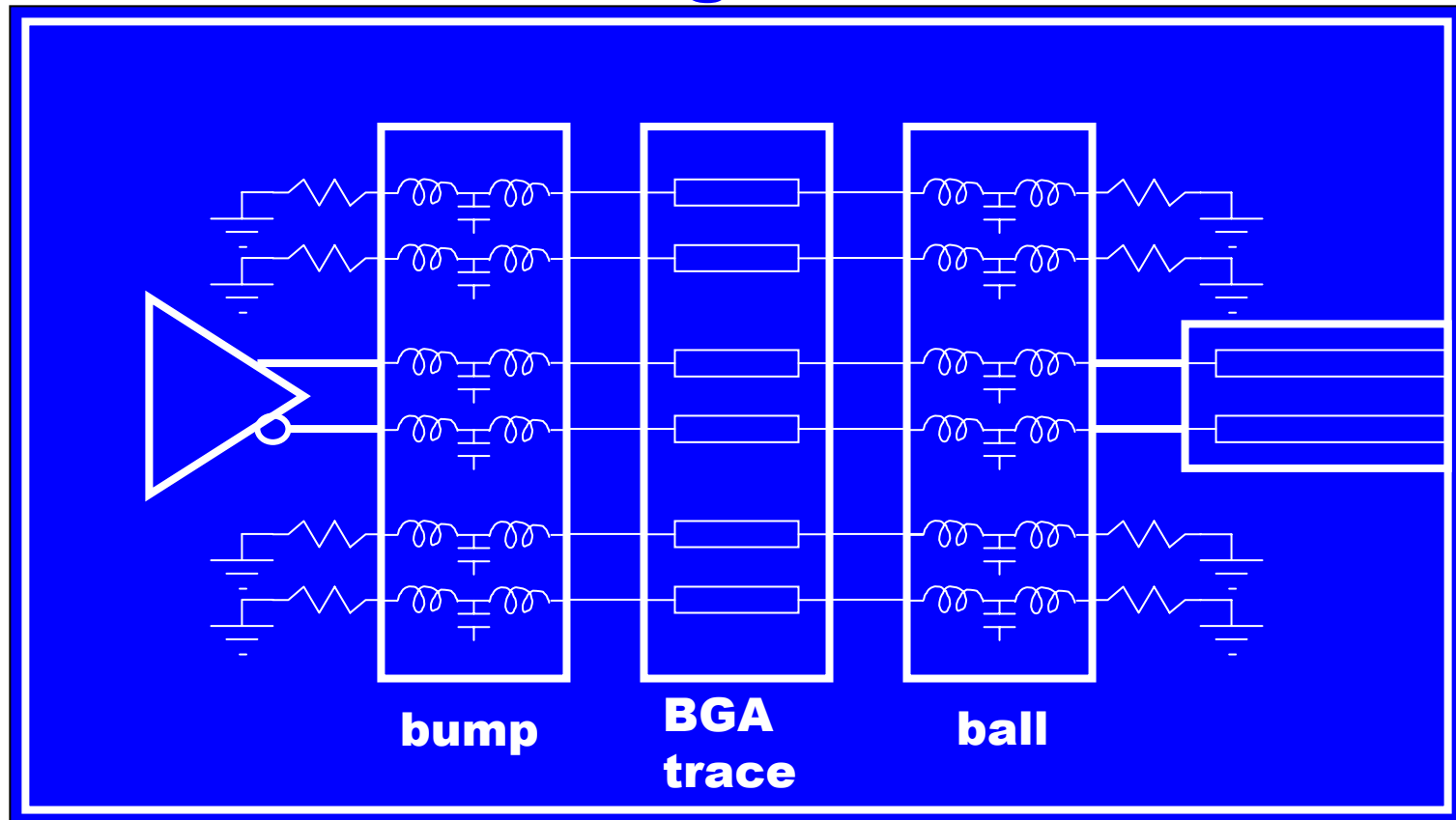
* These are common issues with SPICE models *

Transceiver Model Reduction



- **Driver and Receiver sections separated**
 - Allows instantiation of driver and receiver IBIS 4.1 models on separate parts for design verification
- **Driver section reduced**
 - Data and pre-emphasis signal generation simplified with controlled-source logic
- **Simulation time reduced to 12 minutes real time – 57% of original time**

Package Model

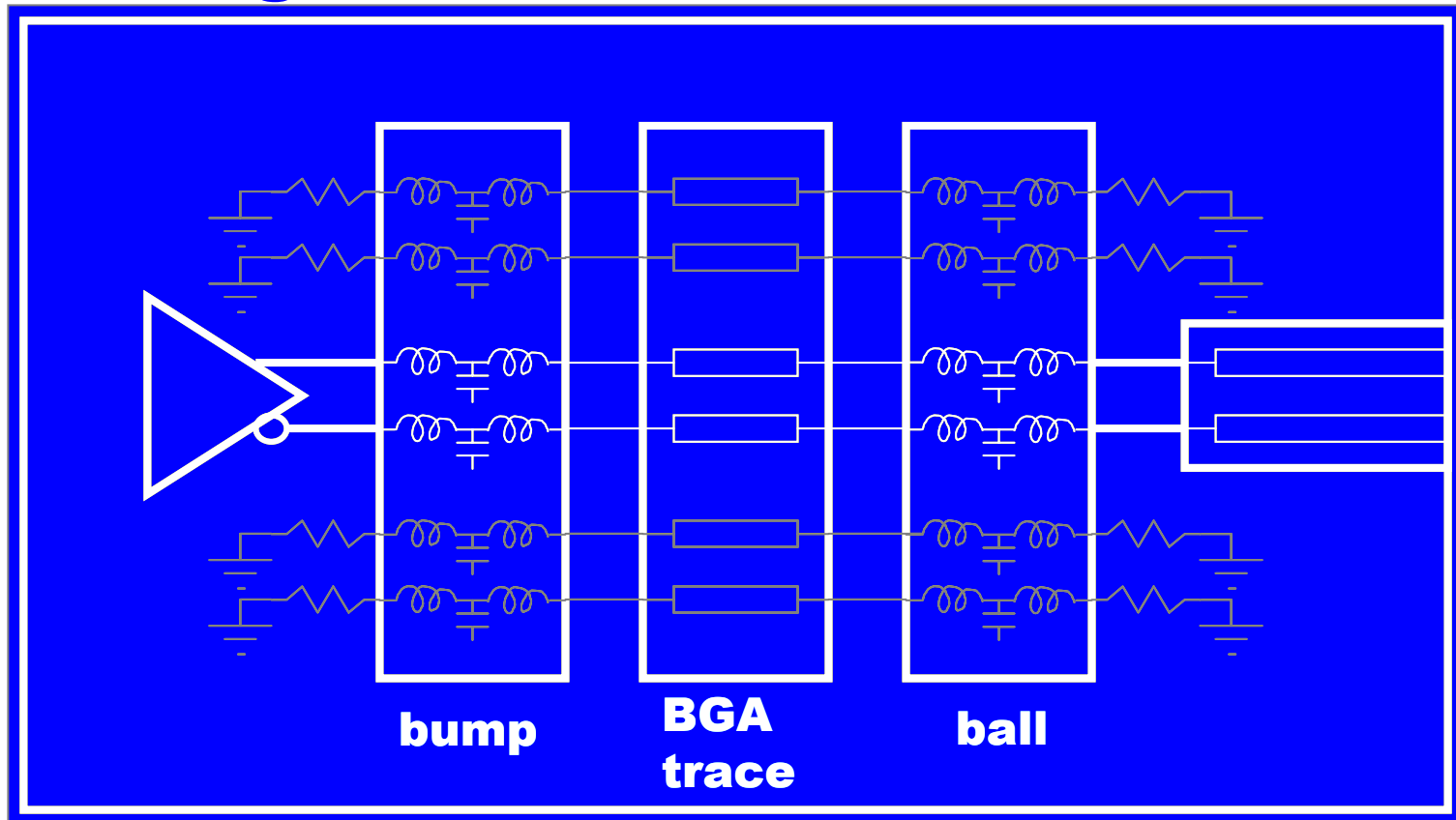


- **Complex package model**
 - 3 differential pairs fully coupled
 - 3 cascaded sections

Package Model Reduction

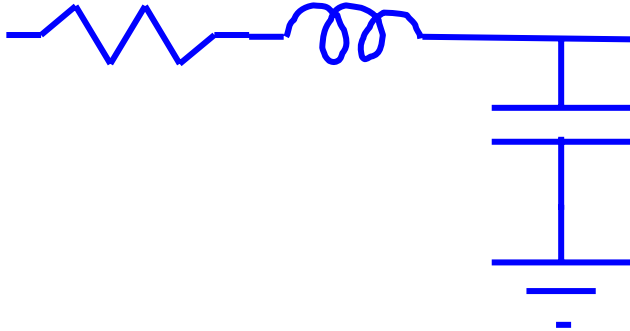
- **Element elimination**
- **Simple IBIS RLC parameters**
- **S-parameter model**

Package Model Element Elimination



- Reduced simulation time by about 10%
- Changed results beyond acceptable error

Simple IBIS RLC Parameters



$$L = T_d * Z$$

$$C = T_d / Z$$

T_d measured from original simulation is 83ps ($T_r \sim 200$ ps)

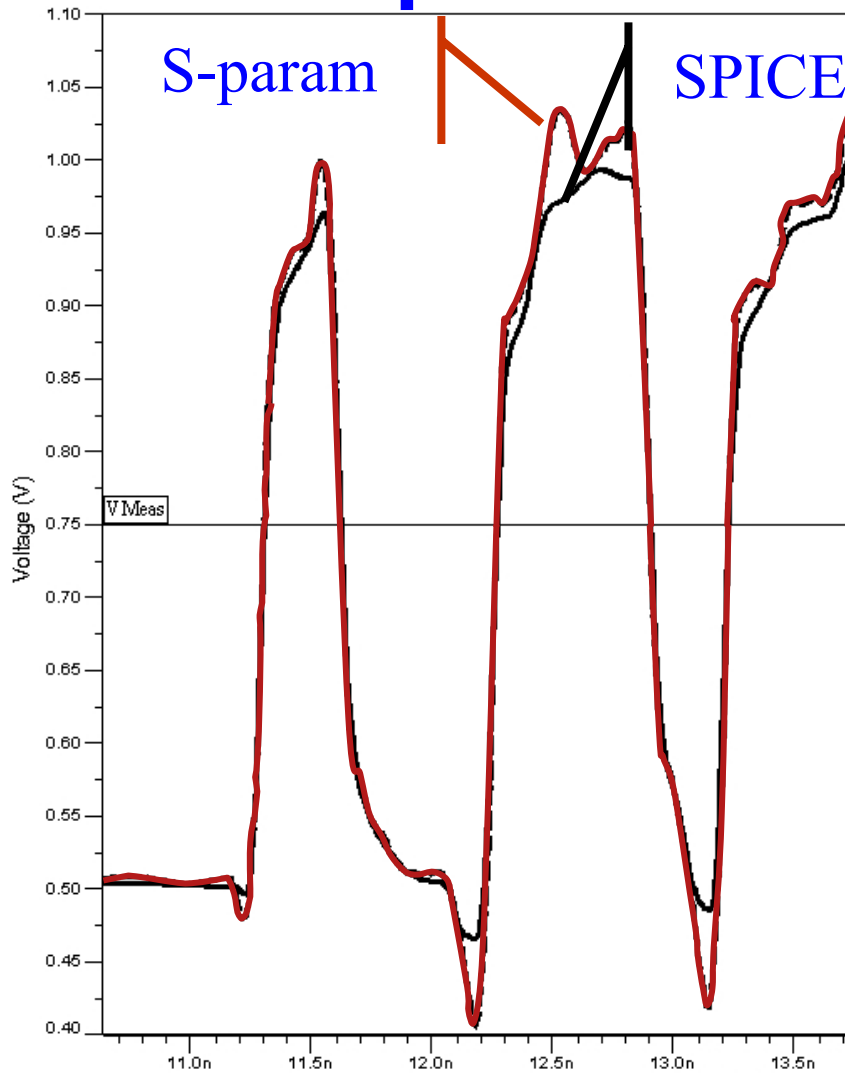
Assume Z_0 is 50 Ω

$$L = 4.15\text{nH}$$

$$C = 1.66\text{pF}$$

- Can't be more accurate than reduced element model
- Should provide much faster simulation time
- Reduced simulation time by 25%
- Reduced overshoot
 - Assumed impedance of 50 Ohms was better than original SPICE model

S-parameter Package Model

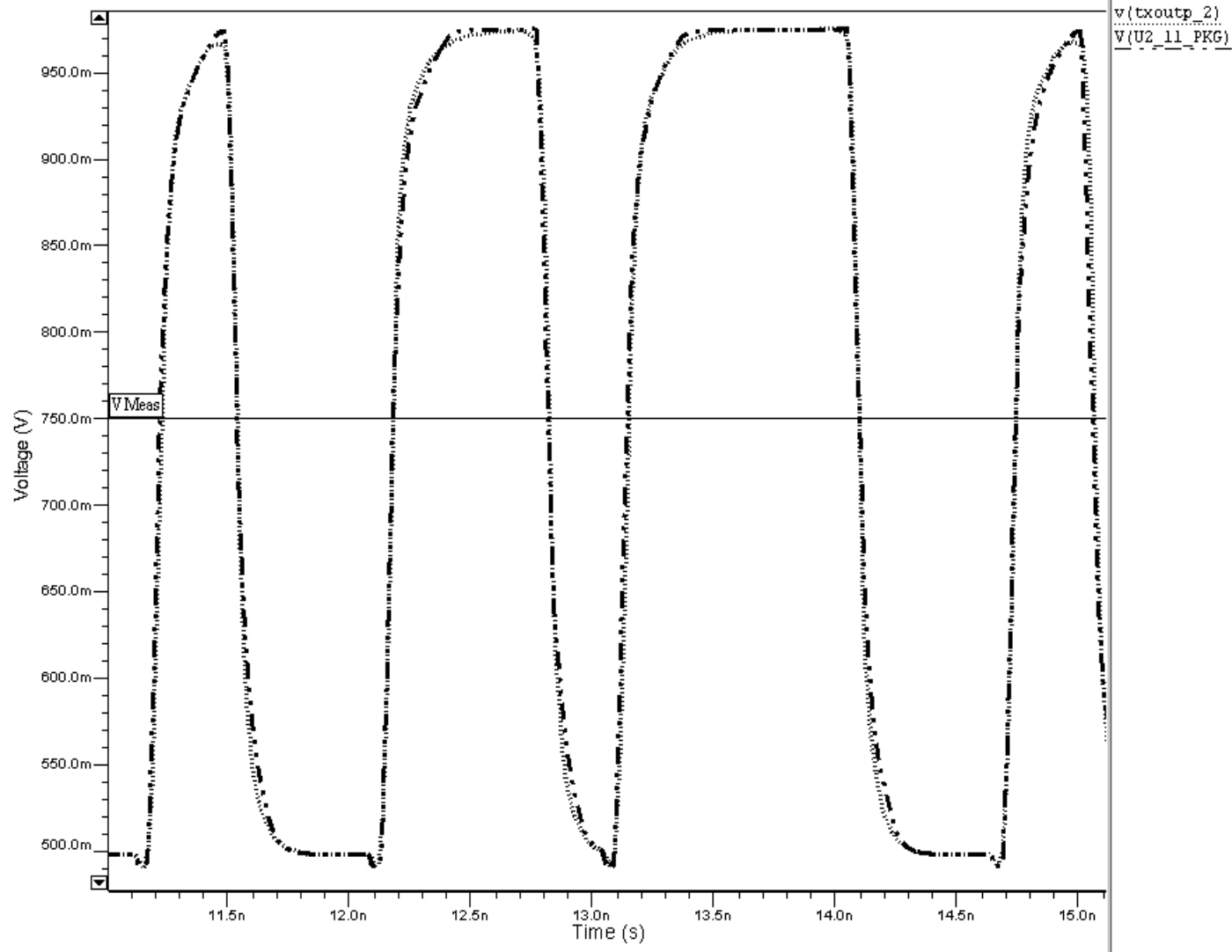


- S-parameter set created by SPICE simulation of original package model
 - Frequency steps of 100MHz from 100MHz up to 10GHz
- Simulation time reduced by 25% from full package model simulation
- S-parameters have other issues
 - Usually no DC information
 - Possible non-causal or non-passive results

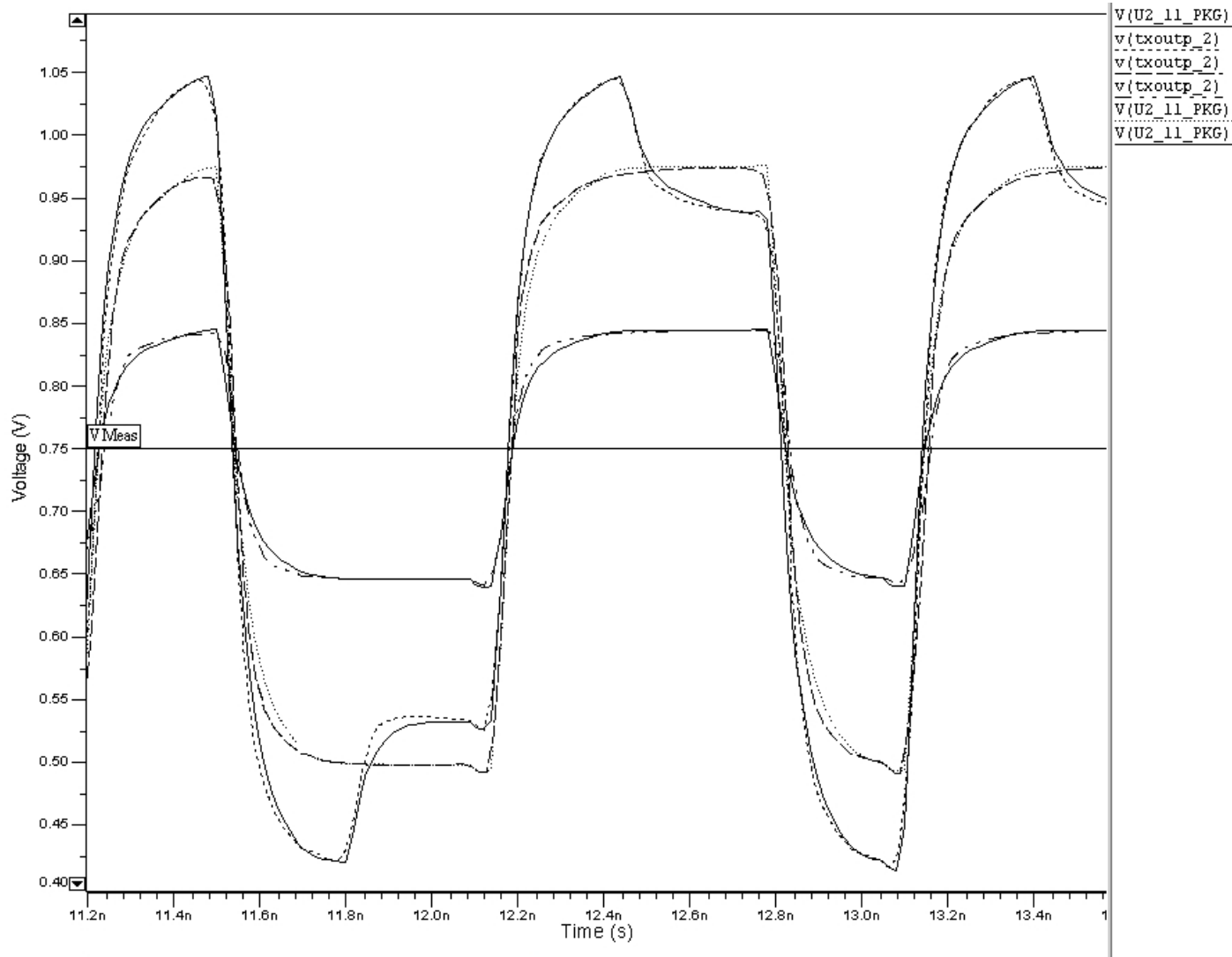
Behavioral Modeling

- *Functionality and accuracy must be maintained!*
- Majority of simulation time is spent solving the 1000's of nodes in the transistor level transmitter and receiver models
- This time could be greatly reduced by using behavioral models such as VHDL-AMS

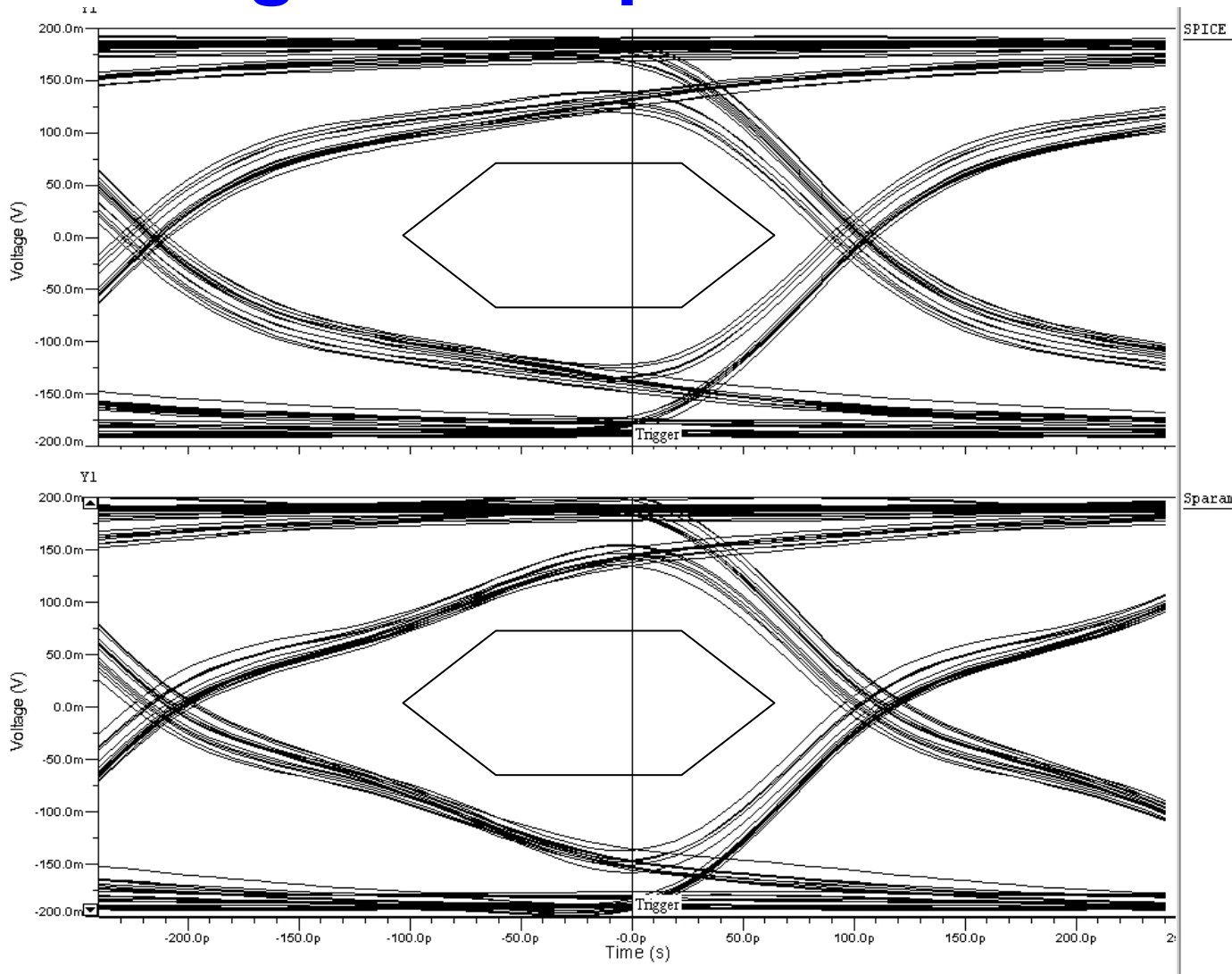
VHDL-AMS Model Correlation



VHDL-AMS Model Functionality



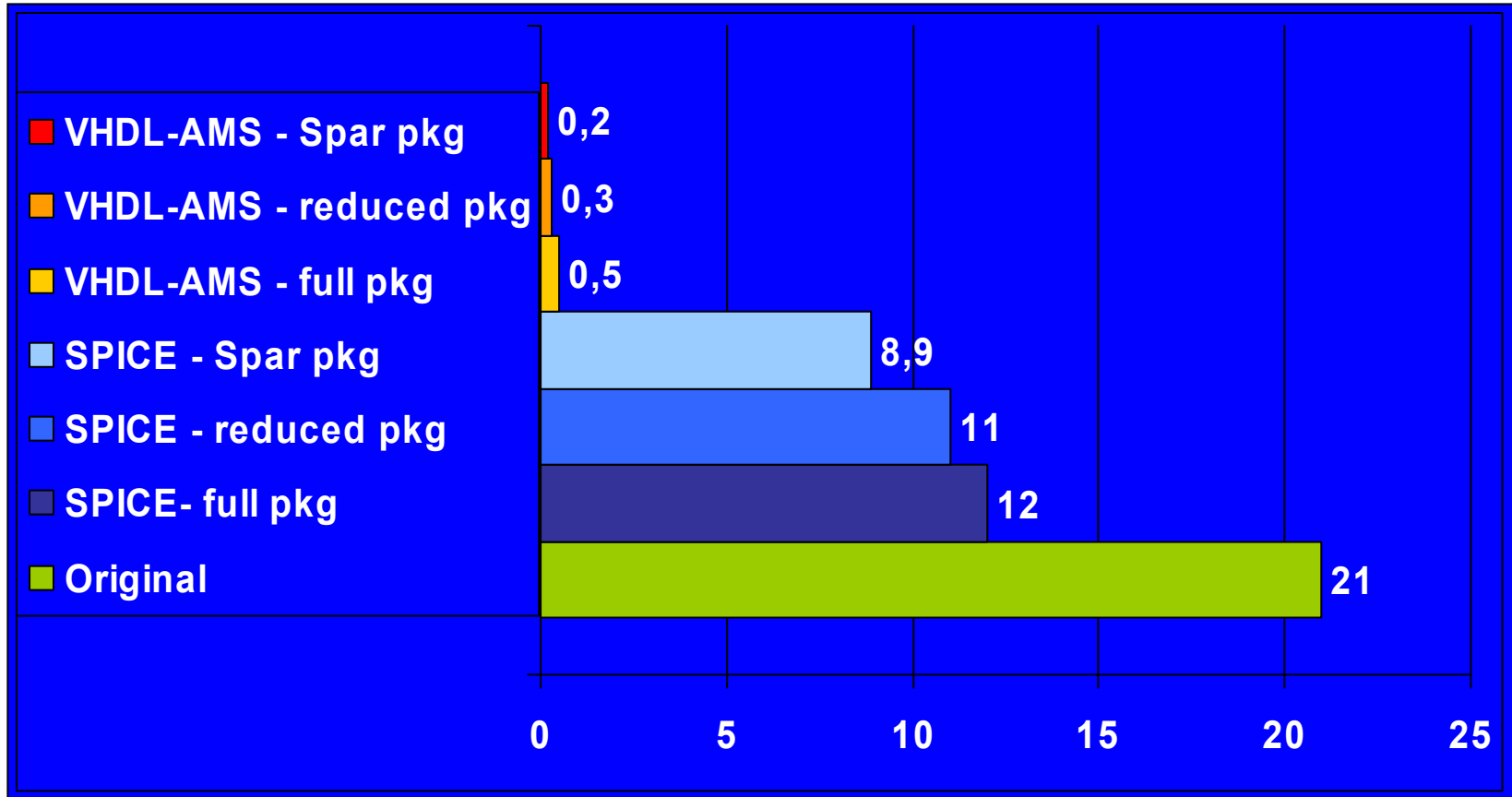
Signal Comparison at the Receiver



SPICE
package

S-param
package

Simulation Time Reduction



Conclusions

- **The SPICE model can be reduced to save simulation time**
- **The package model can be translated to other formats to save some simulation time, but doesn't justify the change in results.**
- **Using a behavioral model of the driver and receiver drastically decreases simulation time to less than 1/10 and maintains fidelity to the original results**
- **Extensions to IBIS and Multi-Lingual Simulator provide flexibility and performance**

Mentor Graphics®

www.mentor.com